

# LEAD FREE SOLDER PASTE

## BZ(L) Standard type

Solder balls reduced to absolute minimum.

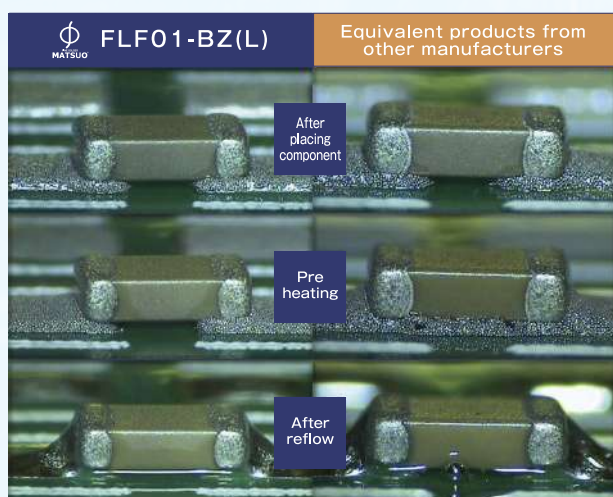
## Fine Solder



## Product Features

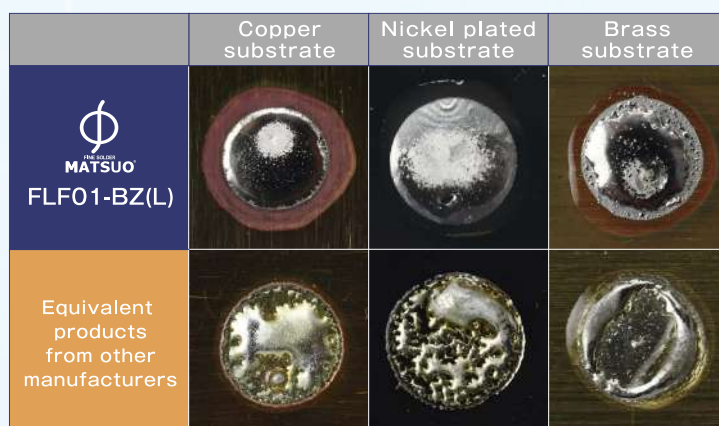
### Significant reduction in solder balls

Our unique flux technology enables the reduction in solder balls by controlling slump (solder outflow beneath components or off the land) during pre-heating.



### Compatible with various types of base materials with good wettability

Our unique activation agent technology provides high solderability and adhesion not just to copper base materials, but also to nickel with its durable oxide film, and brass containing zinc that is hard to spread or absorb.



### Reflow profile conditions

High temperature long pre-heat profile (200°C 2min)

Items	FLF01-BZ (L)	Test method
Alloy composition	Sn96.5%-Ag3.0%-Cu0.5%	JIS Z3282
Solidus temperature	Approx. 217°C	JIS Z3282
Liquidus temperature	Approx. 219°C	JIS Z3282
Particle size	20~38μm(Type4)	JIS Z3284(J-STD-005)
Flux content	11.50%	JIS Z3197
Halide content	0.05%	JIS Z3197
Viscosity	190Pa·s	JIS Z3284
Thixotropy index	0.55	JIS Z3284
Copper plate corrosion test	Pass	JIS Z3197
Insulation resistance test (85°C 85%RH 168hr)	> 5.0×10 <sup>8</sup> Ω	JIS Z3197
Migration test (85°C 85%RH 1,000hr)	Pass	JIS Z3197
Spread rate	88%	JIS Z3197

